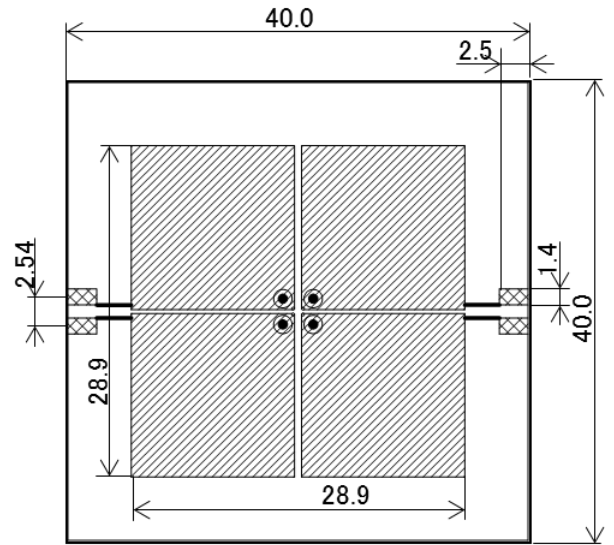


● WLP-4-02 Power Dissipation

Power dissipation data for the WLP-4-02 is shown in this page.  
 The value of power dissipation varies with the mount board conditions.  
 Please use this data as the reference data taken in the following condition.

1. Measurement Condition

- Condition : Mount on a board
- Ambient : Natural convection
- Soldering : Lead (Pb) free
- Board Dimensions : 40 x 40 mm (1600mm<sup>2</sup>)
- Board Structure : 1st Metal layer about 50%  
 2nd Inner Metal layer about 50%  
 3rd Inner Metal layer about 50%  
 4th Metal layer about 50%  
 4 separations is each layer connected to each pin
- Material : Glass Epoxy (FR-4)
- Thickness : 1.6 mm
- Through-hole : 4 x 0.8 Diameter
- Copper foil : 18um



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount (T<sub>j</sub> max = 125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)			θ <sub>ja</sub> (°C/W)
	T <sub>a</sub> max=85°C	T <sub>a</sub> max=105°C	T <sub>a</sub> max=125°C	
25	660	660	660	151.52
85	264	264	264	
105	0	132	132	
125	0	0	0	

